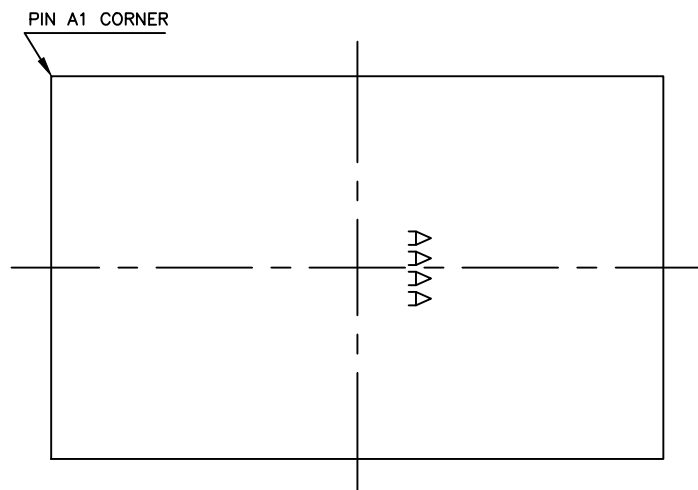
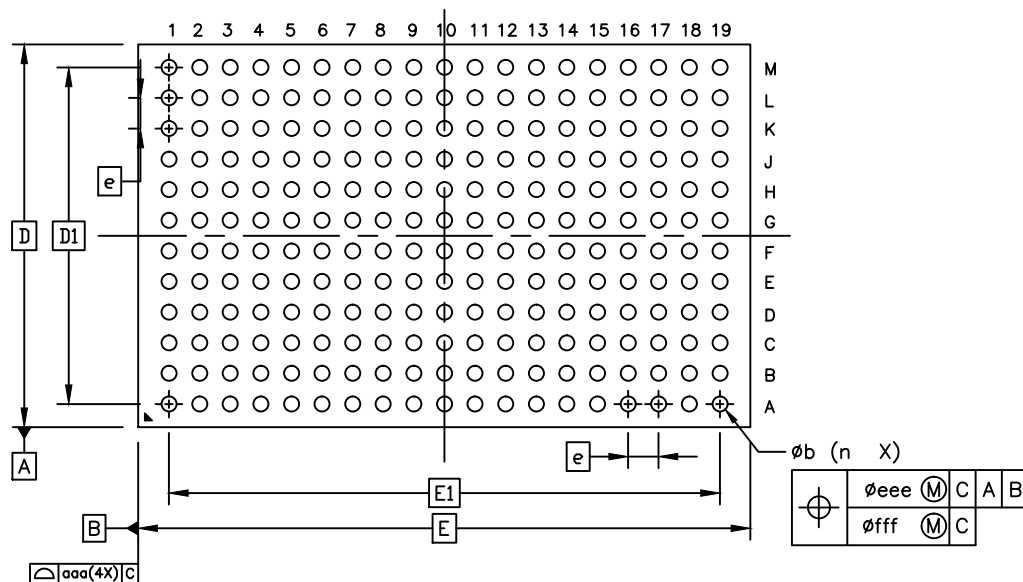
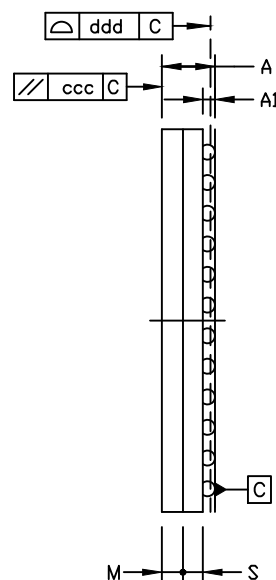


TOP VIEW



SIDE VIEW



BOTTOM VIEW

		Symbol	Common Dimensions		
			MIN.	NOM.	MAX.
Package :			LFBGA		
Body Size:	X	E	16		
	Y	D	10		
Ball Pitch :		e	0.800		
Total Thickness :		A	1.290	1.390	1.490
Mold Thickness :		M	0.550	Ref.	
Substrate Thickness :		S	0.520	Ref.	
Ball Diameter :			0.400		
Stand Off :		A1	0.270	—	0.370
Ball Width :		b	0.370	—	0.470
Package Edge Tolerance :		aaa	0.150		
Mold Parallelism :		ccc	0.200		
Coplanarity:		ddd	0.120		
Ball Offset (Package) :		eee	0.150		
Ball Offset (Ball) :		fff	0.080		
Ball Count :		n	228		
Edge Ball Center to Center :	X	E1	14.400		
	Y	D1	8.800		

NOTES:

1. DIMENSION *b* IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE C.
2. DATUM C (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
3. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
4. PACKAGE CODE: X22860+4



TITLE:
PACKAGE OUTLINE, 228 BALLS CSBGA
16x10x1.39 mm

APPROVAL DIVYA CHOUDHARY	DOCUMENT CONTROL NO. 21-100542	REV. A	1/1
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—DRAWING NOT TO SCALE—